



PK644 (v1.0) April 4, 2014

100% Material Declaration Data Sheet for Spartan 3A DSP FGG676 Package

Average Weight: 3.2060g

Component	Substance Description	CAS Number or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.083924	2.618
	Silicon	7440-21-3	100.00		0.083924	
Silver Epoxy					0.014829	0.463
	Silver	7440-22-4	77.50		0.011492	
	Bismaleimide monomer	Trade Secret	15.00		0.002224	
	Acrylate monomer	Trade Secret	7.50		0.001112	
Mold Compound					1.379825	43.039
	Epoxy Resin A	Trade Secret	3.00		0.041395	
	Epoxy Resin B	Trade Secret	3.00		0.041395	
	Phenol Resin	Trade Secret	3.00		0.041395	
	Silica(Amorphous)A	60676-86-0	72.45		0.999683	
	Silica(Amorphous)B	7631-86-9	15.00		0.206974	
	Metal Hydroxide	Trade Secret	3.00		0.041395	
	Carbon Black	1333-86-4	0.55		0.007589	
Copper Wire					0.007841	0.245
	Copper	7440-50-8	98.25		0.007704	
	Palladium	7440-05-3	1.75		0.000137	
Solder Ball					0.566235	17.662
	Tin	7440-31-5	95.50		0.540754	
	Silver	7440-22-4	4.00		0.022649	
	Copper	7440-50-8	0.50		0.002831	
Substrate					1.153346	35.975
	Gold	7440-57-5	0.23		0.002614	
	Nickel	7440-02-0	1.74		0.020110	
	Copper Foil	7440-50-8	49.72		0.573391	
	Copper Plating	7440-50-8	8.12		0.093599	
	BT Core	65997-17-3 / 105391-33-1 / 25722-66-1 / 9003-36-5 / 21645-51-2	33.62		0.387769	
	Solder Mask	34590-94-8 / 7727-43-7	6.58		0.075862	

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Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
04/04/14	1.0	Initial Xilinx release.

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